

Product Summary

V_{RRM}	650 V
$I_F (T_C=155^{\circ}C)$	10 A
Q_C	29 nC

Features

- Extremely low reverse current
- No reverse recovery current
- Temperature independent switching
- Positive temperature coefficient on V_F
- Excellent surge current capability
- Low capacitive charge

Benefits

- Essentially no switching losses
- System efficiency improvement over Si diodes
- Increased power density
- Enabling higher switching frequency
- Reduction of heat sink requirements
- System cost savings due to smaller magnetics
- Reduced EMI

Applications

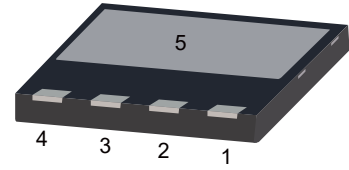
- Switch mode power supplies (SMPS)
- Uninterruptible power supplies
- Motor drivers
- Power factor correction

Package Pin Definitions

- Pin 1,2 - NC
- Pin 3,4 - Anode
- Pin 5 - Cathode

Package Parameters

Part Number	Marking	Package
B2D10065Q	B2D10065Q	DFN 8*8

Package: DFN 8*8

Electrical Connection


Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test conditions	Value	Unit
V_{RRM}	Repetitive peak reverse voltage		650	V
V_{RSM}	Non-repetitive peak reverse voltage		650	V
I_F	Continuous forward current	$T_c=25^\circ\text{C}$ $T_c=155^\circ\text{C}$	34 10	A
I_{FSM}	Non-repetitive forward surge current	$T_c=25^\circ\text{C}$, $t_p=10\text{ms}$ Half sine wave	70	A
$\int i^2 dt$	i^2t value	$T_c=25^\circ\text{C}$, $t_p=10\text{ms}$	24.5	A^2S
P_{tot}	Power dissipation	$T_c=25^\circ\text{C}$ $T_c=110^\circ\text{C}$	126 54	W
T_j	Operating junction temperature		-55~175	$^\circ\text{C}$
T_{stg}	Storage temperature		-55~175	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
$R_{th(jc)}$	Thermal resistance from junction to case		1.182		K/W

Electrical Characteristics
Static Characteristics

Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
V_{DC}	DC blocking voltage	$T_J=25^{\circ}C$	650			V
V_F	Diode forward voltage	$I_F=10A$ $T_J=25^{\circ}C$ $I_F=10A$ $T_J=175^{\circ}C$		1.33 1.67	1.5 2.3	V
I_R	Reverse current	$V_R=650V$ $T_J=25^{\circ}C$ $V_R=650V$ $T_J=175^{\circ}C$		2 20	70 200	μA

AC Characteristics

Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
Q_C	Total capacitive charge	$V_R=400V$ $T_J=25^{\circ}C$ $Q_C=\int_0^{V_R} C(V)dV$		29		nC
C	Total capacitance	$V_R=1V$ $f=1MHz$ $V_R=300V$ $f=1MHz$ $V_R=600V$ $f=1MHz$		457 49.7 49.3		pF
E_C	Capacitance stored energy	$V_R=400V$		7.5		μJ

Typical Performance

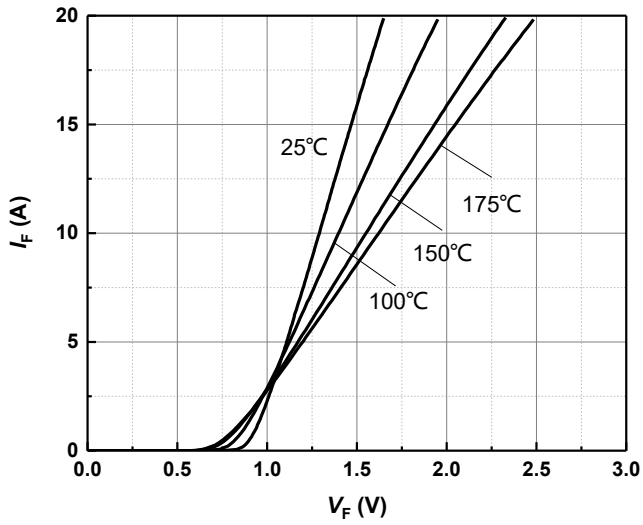


Figure 1 Typical forward characteristics

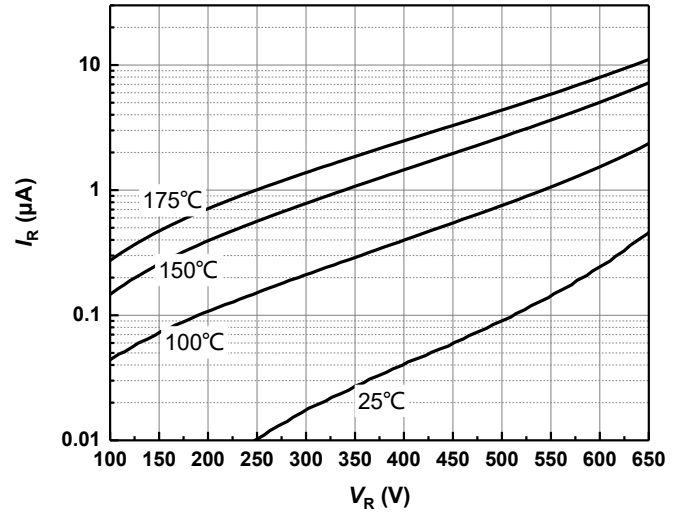


Figure 2 Typical reverse current as function of reverse voltage

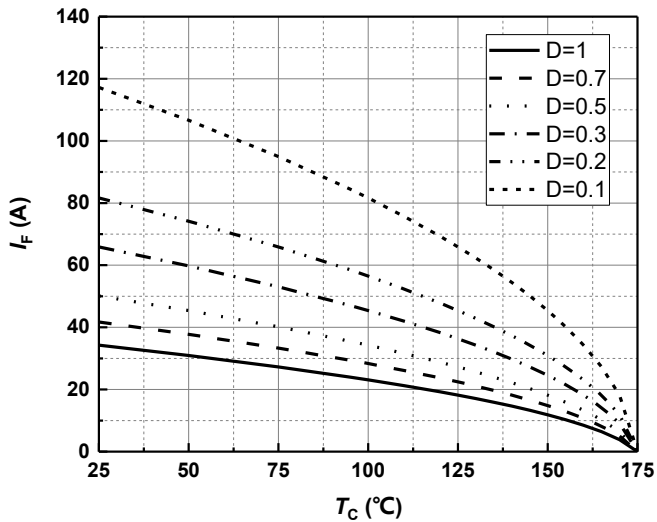


Figure 3 Diode forward current as function of temperature, D =duty cycle

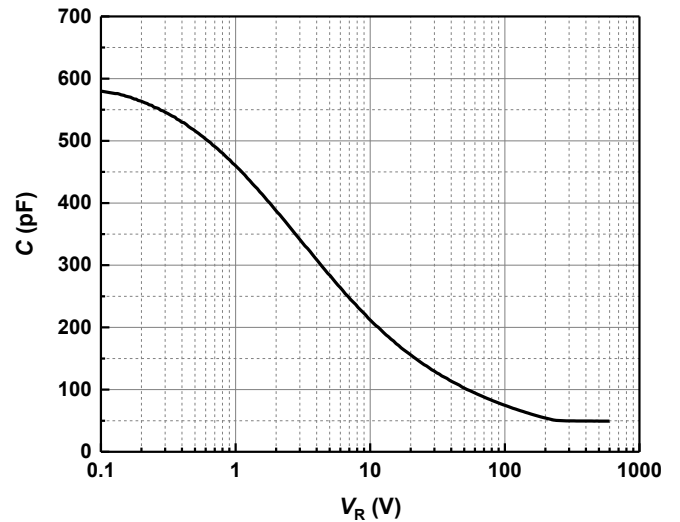


Figure 4 Typical capacitance as function of reverse voltage, $C=f(V_R)$; $T_J=25^\circ\text{C}$; $f=1\text{ MHz}$

Typical Performance

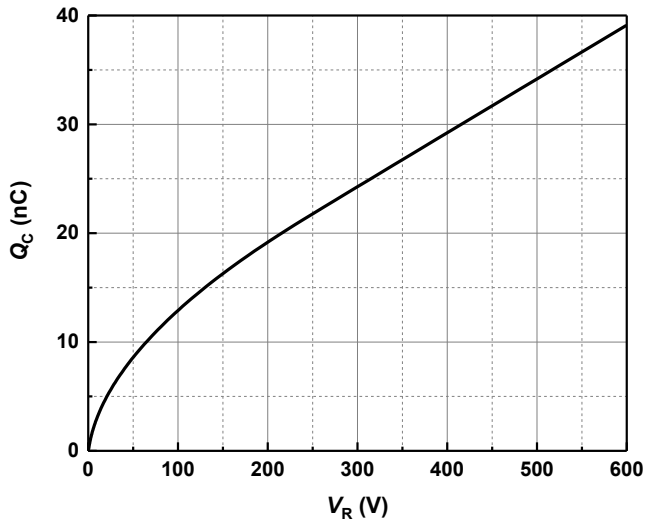


Figure 5 Typical reverse charge as function of reverse voltage

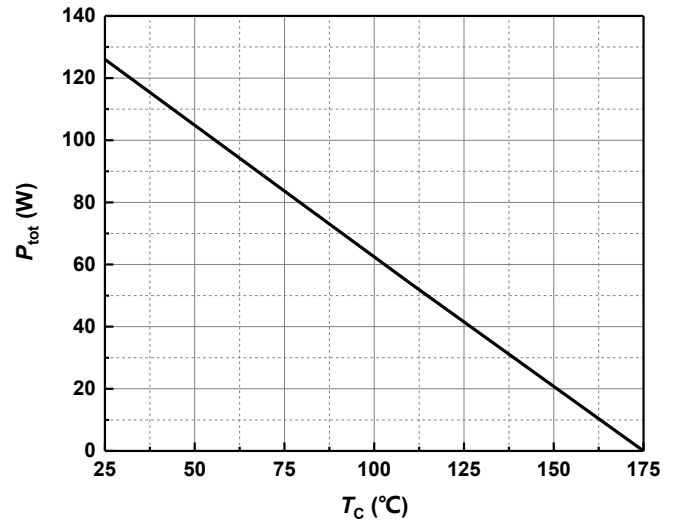


Figure 6 Power dissipation as function of case temperature

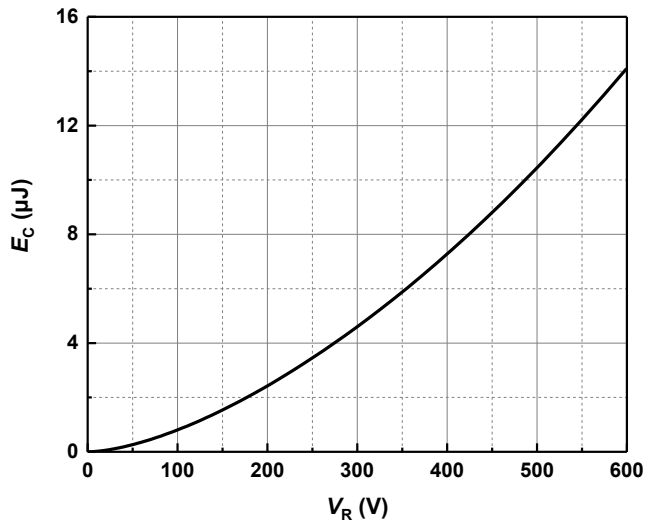


Figure 7 Capacitance stored energy

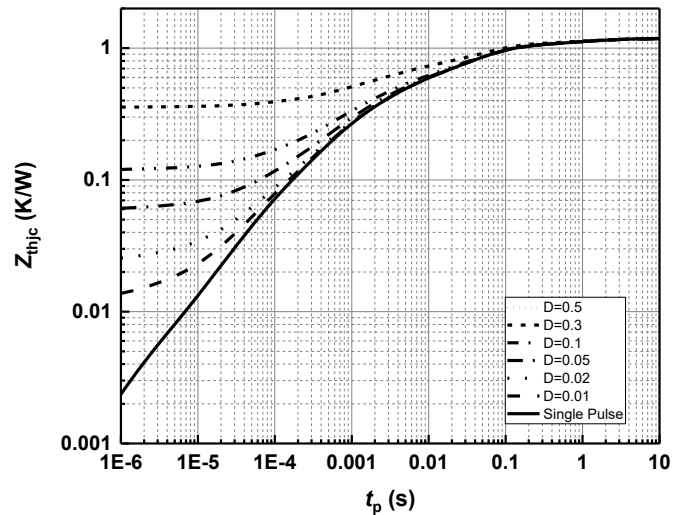
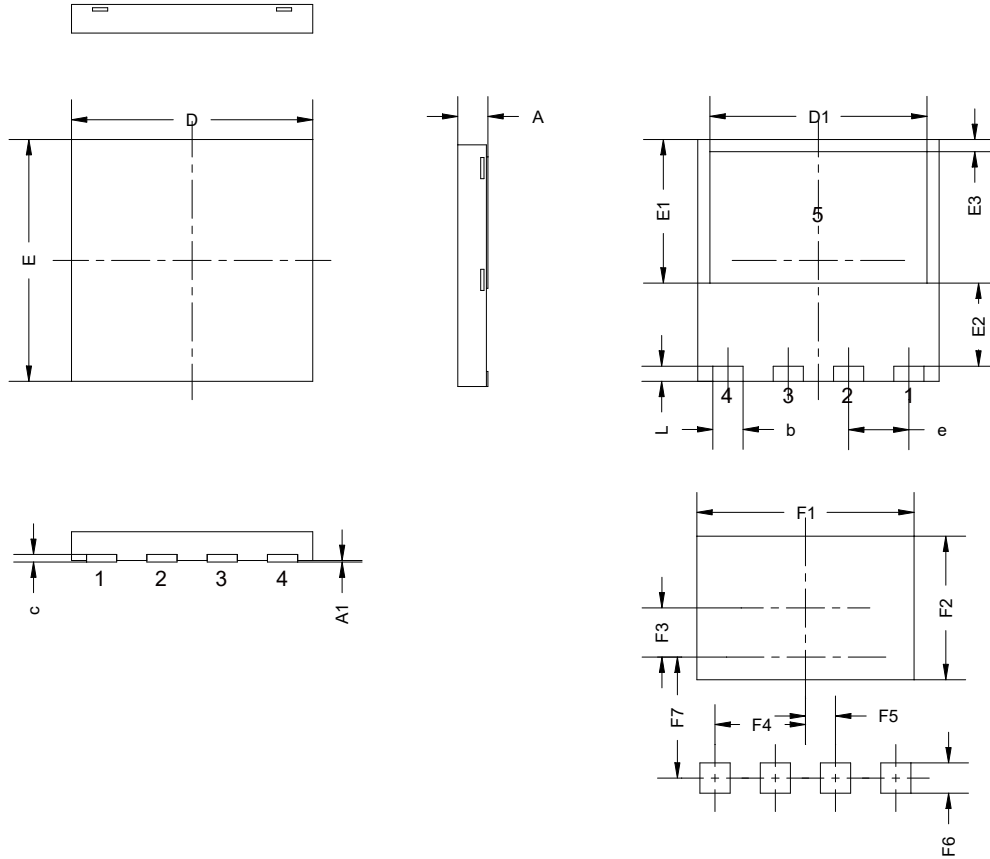


Figure 8 Max. transient thermal impedance, $Z_{thjc} = f(t_p)$, parameter: $D = t_p / T$

Package Dimensions



SYMBOL	mm		
	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	-	0.05
b	0.90	1.00	1.10
c	0.10	0.20	0.30
D	7.90	8.00	8.10
D1	7.10	7.20	7.30
E	7.90	8.00	8.10
E1	4.65	4.75	4.85
E2	2.65	2.75	2.85
E3	0.30	0.40	0.50
e	2.00 BSC		
L	0.40	0.50	0.60
F1	-	7.20	-
F2	-	4.75	-
F3	-	1.43	-
F4	-	3.00	-
F5	-	1.00	-
F6	-	1.00	-
F7	-	4.20	-

Revision History

Document Version	Date of Release	Description of Changes
Rev. 1.0	2021-10-21	Release of the datasheet.
Rev. 1.1	2022-10-11	Characteristics updated.

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Shenzhen, China
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